

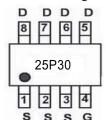
RM25P30S8

P-Channel Enhancement Mode Power MOSFET

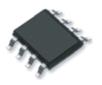
Description

The RM25P30S8 uses advanced trench technology to provide excellent $R_{\text{DS(ON)}}$, This device is suitable for use as a load switch or power management.

Schematic diagram



Marking and pin assignment



SOP-8 top view

General Features

• $V_{DS} = -30V, I_{D} = -25A$ $R_{DS(ON)}$ <9m Ω @ V_{GS} =-10V

- High power and current handing capability
- Lead free product is acquired
- Surface mount package

Application

- Power management
- Load switch

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
25P30	RM25P30S8	SOP-8	Ø330mm	12mm	2500

Absolute Maximum Ratings (T_A=25°Cunless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	-30	V	
Gate-Source Voltage	V _G s	±20	V	
Drain Current-Continuous	I _D	-25	А	
Drain Current-Pulsed (Note 1)	I _{DM}	-70	А	
Maximum Power Dissipation	P _D	3.5	W	
Operating Junction and Storage Temperature Range	T_J,T_STG	-55 To 150	°C	

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	36	°C/W

Electrical Characteristics (T_A=25°Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit		
Off Characteristics								
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-30	-33	-	V		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-30V,V _{GS} =0V	-	-	-1	μA		

Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA	
On Characteristics (Note 3)							
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =-250μA	-1.0	-1.5	-2.5	V	
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-10V, I _D =-15A	-	6.4	9	mO.	
Dialii-Source Off-State Resistance	R _{DS(ON)}	V _{GS} =-4.5V, I _D =-10A	-	8.3	14	1	11112
Forward Transconductance	g FS	V _{DS} =-10V,I _D =-15A	30	-	-	S	
Dynamic Characteristics (Note4)							
Input Capacitance	C _{lss}	\/ - 15\/\/ -0\/	-	3960	-	PF	
Output Capacitance	Coss	V_{DS} =-15V, V_{GS} =0V, F=1.0MHz	-	486	-	PF	
Reverse Transfer Capacitance	C _{rss}	- F-1.UIVITZ	-	268	-	PF	
Switching Characteristics (Note 4)							
Turn-on Delay Time	t _{d(on)}		-	20	-	nS	
Turn-on Rise Time	t _r	V _{DD} =-15V, ID=-10A,	-	13	-	nS	
Turn-Off Delay Time	t _{d(off)}	V_{GS} =-10V, R_{GEN} =3 Ω	-	55	-	nS	
Turn-Off Fall Time	t _f		-	21	-	nS	
Total Gate Charge	Qg		-	65	-	nC	
Gate-Source Charge	Q _{gs}	V _{DS} =-15V,I _D =-10A,V _{GS} =-10V	-	12	-	nC	
Gate-Drain Charge	Q _{gd}	1	-	14	-	nC	
Drain-Source Diode Characteristics		•	•	•			
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =-25A	-	-	-1.2	V	
				•			

Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- **3.** Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production



RATING AND CHARACTERISTICS CURVES (RM25P30S8)

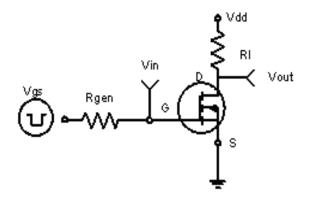


Figure 1 Switching Test Circuit

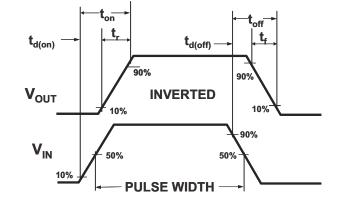


Figure 2 Switching Waveforms

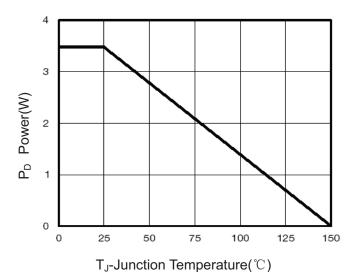


Figure 3 Power Dissipation

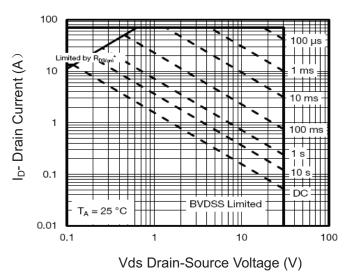


Figure 4 Safe Operation Area

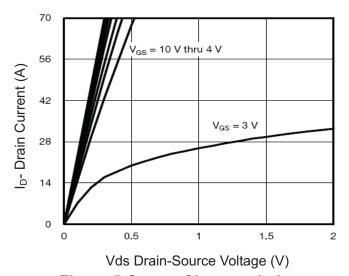


Figure 5 Output Characteristics

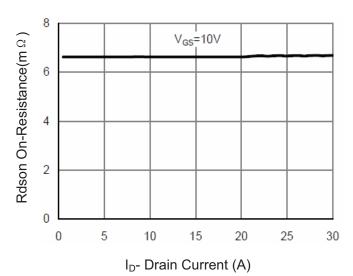


Figure 6 Drain-Source On-Resistance



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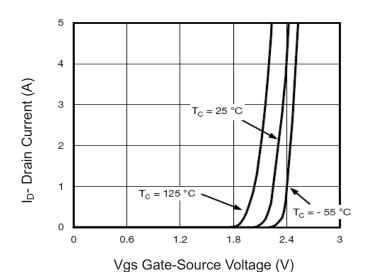
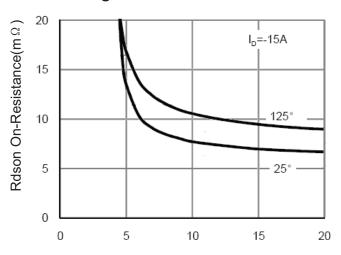


Figure 7 Transfer Characteristics



Vgs Gate-Source Voltage (V)
Figure 9 Rdson vs Vgs

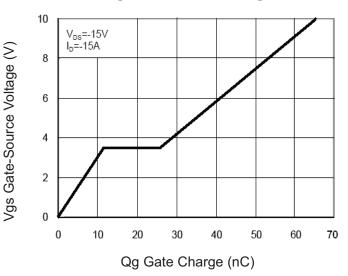


Figure 11 Gate Charge

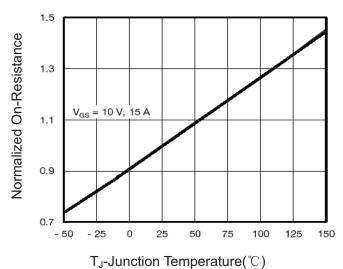


Figure 8 Drain-Source On-Resistance

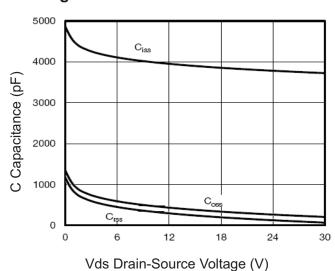


Figure 10 Capacitance vs Vds

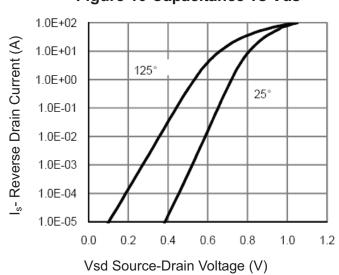


Figure 12 Source- Drain Diode Forward



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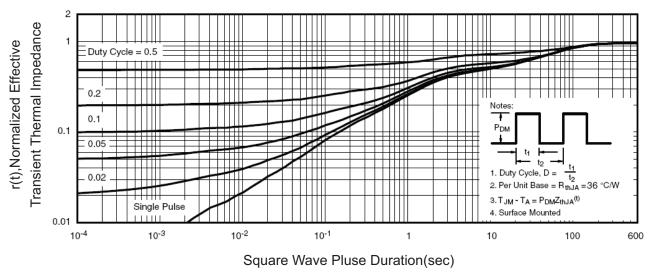
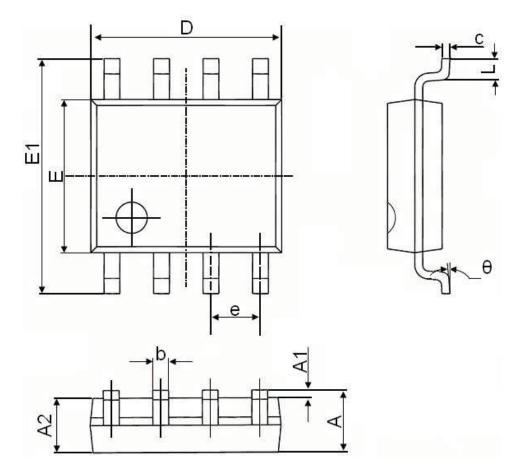


Figure 13 Normalized Maximum Transient Thermal Impedance



SOP-8 Package Information



Cymbal	Dimensions I	n Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
С	0.170	0.250	0.006	0.010	
D	4.700	5.100	0.185	0.200	
Е	3.800	4.000	0.150	0.157	
E1	5.800	6.200	0.228	0.244	
е	1.270	(BSC)	0.050	(BSC)	
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	



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